

Specification

MATERIAL:

Insulator: High Temperature Thermoplastic,
UL 94V-0.
Contact: Copper Alloy

PLATING:

Contact: Plated 50u'' Ni Overall
Plated Au Selective Contact Area
Plated 100u'' Sn Over Ni On Solder Area
Shell: Plated 50u'' Ni Overall
Plated 1u'' Au Over Ni On Solder Area

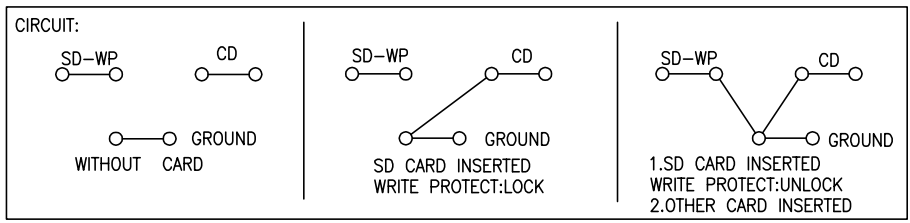
Electrical:

Current Rating :0.5mA AC/DC max.
Voltage Rating :125V AC/DC
Ambient Temperature Range :-20°C~+60°C
Storage Temperature Range :-40°C~+70°C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩ max.
Insulation Resistance:1000MΩ min./500VDC
Mating Cycles:10,000 Insertions

Usable Memory Card:

SD&MMC Card

Pin No.		SD	MMC
P1	MMC-DAT SD-DAT3	1P	7P
P2	MMC-CMD SD-CMD	2P	2P
P3	MMC-VSS1 SD-VSS1	3P	3P
P4	MMC-VDD SD-VDD	4P	4P
P5	MMC-CLK SD-CLK	5P	5P
P6	MMC-VSS2 SD-VSS2	6P	6P
P7	MMC-DAT SD-DAT0	7P	1P
P8	SD-DAT1	8P	
P9	SD-DAT2	9P	



DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE DIMENSION TOLERANCE X.X: ± 0.25 X.XX: ± 0.10 X.XXX: ± 0.05 ANGULAR: ± 1°	PRODUCT NAME : SD push-push	DRAWING:	DATE: 2008/12/10
	PRODUCT NO. : SD-001-001	CHECK: H.Z	DATE: 2008/12/10
	DRAWING NO. : NT-001	APPROVED	DATE: 2008/12/10
	SCALE: 1:1	DWG ID: P D	REV.: A

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				
2				
3				